

# International **IR** Rectifier HEXFET® POWER MOSFET

Provisional Data Sheet No. PD 9.1292B

**IRFY440CM**

**N-CHANNEL**

## 500 Volt, 0.85Ω HEXFET

HEXFET technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry design achieves very low on-state resistance combined with high transconductance.

HEXFET transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching, ease of paralleling and electrical parameter temperature stability. They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers, high energy pulse circuits, and virtually any application where high reliability is required.

The HEXFET transistor's totally isolated package eliminates the need for additional isolating material between the device and the heatsink. This improves thermal efficiency and reduces drain capacitance.

## Product Summary

Part Number	BVDSS	RDS(on)	ID
IRFY440CM	500V	0.85Ω	7.0A

## Features

- Hermetically sealed
- Electrically isolated
- Simple Drive Requirements
- Ease of Paralleling
- Ceramic eyelets

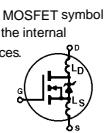
## Absolute Maximum Ratings

Parameter	IRFY440CM	Units
I <sub>D</sub> @ V <sub>GS</sub> =10V, T <sub>C</sub> = 25°C	Continuous Drain Current	7.0
I <sub>D</sub> @ V <sub>GS</sub> =10V, T <sub>C</sub> = 100°C	Continuous Drain Current	4.4
I <sub>DM</sub>	Pulsed Drain Current ①	28
P <sub>D</sub> @ T <sub>C</sub> = 25°C	Max. Power Dissipation	100
	Linear Derating Factor	0.8
V <sub>GS</sub>	Gate-to-Source Voltage	±20
EAS	Single Pulse Avalanche Energy ②	510
I <sub>AR</sub>	Avalanche Current ①	7.0
E <sub>AR</sub>	Repetitive Avalanche Energy ①	10
dv/dt	Peak Diode Recovery dv/dt ③	V/ns
T <sub>J</sub>	Operating Junction	-55 to 150
T <sub>stg</sub>	Storage Temperature Range	°C
	Lead Temperature	300 (0.063 in (1.6mm) from case for 10 sec)
	Weight	4.3(typical) g

# IRFY440CM Device

## Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (Unless Otherwise Specified)

Parameter	Min	Typ	Max	Units	Test Conditions
$\text{BV}_{\text{DSS}}$	Drain-to-Source Breakdown Voltage	500	—	—	V $\text{V}_{\text{GS}} = 0\text{V}, \text{I}_D = 1.0\text{mA}$
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Temperature Coefficient of Breakdown Voltage	—	0.78	—	V/ $^\circ\text{C}$ Reference to $25^\circ\text{C}, \text{I}_D = 1.0\text{mA}$
$\text{R}_{\text{DS(on)}}$	Static Drain-to-Source	—	—	0.85	$\Omega$ $\text{V}_{\text{GS}} = 10\text{V}, \text{I}_D = 4.4\text{A}$ ④ $\text{V}_{\text{GS}} = 10\text{V}, \text{I}_D = 7.0\text{A}$
	On-State Resistance	—	—	0.95	
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	2.0	—	4.0	V $\text{V}_{\text{DS}} = \text{V}_{\text{GS}}, \text{I}_D = 250\mu\text{A}$
$\text{g}_{\text{fs}}$	Forward Transconductance	4.7	—	—	S ( $\text{mS}$ ) $\text{V}_{\text{DS}} \geq 15\text{V}, \text{I}_{\text{DS}} = 4.4\text{A}$ ④
$\text{I}_{\text{DSS}}$	Zero Gate Voltage Drain Current	—	—	25	$\mu\text{A}$ $\text{V}_{\text{DS}} = 0.8 \times \text{max. rating}, \text{V}_{\text{GS}} = 0\text{V}$ $\text{V}_{\text{DS}} = 0.8 \times \text{max. rating}$ $\text{V}_{\text{GS}} = 0\text{V}, T_J = 125^\circ\text{C}$
		—	—	250	
$\text{I}_{\text{GSS}}$	Gate-to-Source Leakage Forward	—	—	100	nA $\text{V}_{\text{GS}} = 20\text{V}$ $\text{V}_{\text{GS}} = -20\text{V}$
$\text{I}_{\text{GSS}}$	Gate-to-Source Leakage Reverse	—	—	-100	
$\text{Q}_g$	Total Gate Charge	27.3	—	68.5	nC $\text{V}_{\text{GS}} = 10\text{V}, \text{I}_D = 7.0\text{A}$ $\text{V}_{\text{DS}} = \text{Max. Rating} \times 0.5$ see figures 6 and 13
$\text{Q}_{\text{gs}}$	Gate-to-Source Charge	2.0	—	12.5	
$\text{Q}_{\text{gd}}$	Gate-to-Drain ('Miller') Charge	11.1	—	42.4	
$\text{t}_{\text{d(on)}}$	Turn-On Delay Time	—	—	21	
$\text{t}_{\text{r}}$	Rise Time	—	—	73	ns $\text{V}_{\text{DD}} = 250\text{V}, \text{I}_D = 7.0\text{A}, \text{R}_G = 9.1\Omega$ $\text{V}_{\text{GS}} = 10\text{V}$ see figure 10
$\text{t}_{\text{d(off)}}$	Turn-Off Delay Time	—	—	72	
$\text{t}_{\text{f}}$	Fall Time	—	—	51	
$\text{L}_{\text{D}}$	Internal Drain Inductance	—	8.7	—	nH Measured from the drain lead, 6mm (0.25 in.) from package to center of die.
$\text{L}_{\text{S}}$	Internal Source Inductance	—	8.7	—	
$\text{C}_{\text{iss}}$	Input Capacitance	—	1300	—	pF $\text{V}_{\text{GS}} = 0\text{V}, \text{V}_{\text{DS}} = 25\text{V}$ $f = 1.0\text{MHz}$ . see figure 5
$\text{C}_{\text{oss}}$	Output Capacitance	—	310	—	
$\text{Crss}$	Reverse Transfer Capacitance	—	120	—	



## Source-Drain Diode Ratings and Characteristics

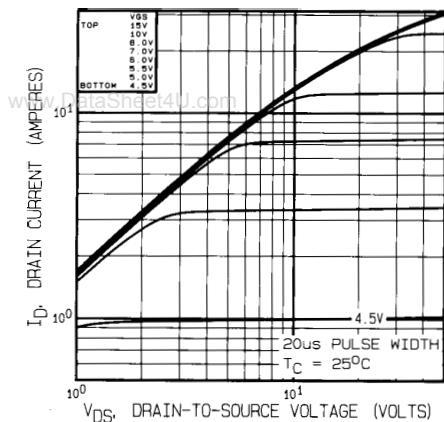
Parameter	Min	Typ	Max	Units	Test Conditions
$\text{I}_S$	Continuous Source Current (Body Diode)	—	—	7.0	A Modified MOSFET symbol showing the integral reverse p-n junction rectifier.
$\text{ISM}$	Pulse Source Current (Body Diode) ④	—	—	28	
$\text{V}_{\text{SD}}$	Diode Forward Voltage	—	—	1.5	V $T_J = 25^\circ\text{C}, \text{I}_S = 7.0\text{A}, \text{V}_{\text{GS}} = 0\text{V}$ ④
$\text{trr}$	Reverse Recovery Time	—	—	700	ns $T_J = 25^\circ\text{C}, \text{I}_F = 7.0\text{A}, \text{dI/dt} \leq 100 \text{ A}/\mu\text{s}$
$\text{QRR}$	Reverse Recovery Charge	—	—	8.9	$\mu\text{C} \text{ V}_{\text{DD}} \leq 50\text{V}$ ④
$\text{ton}$	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $\text{L}_S + \text{L}_D$ .			



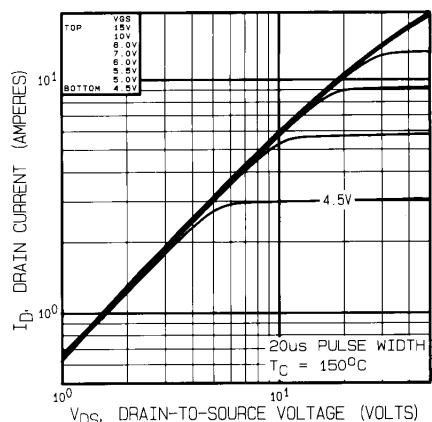
## Thermal Resistance

Parameter	Min	Typ	Max	Units	Test Conditions
$\text{R}_{\text{thJC}}$	Junction-to-Case	—	—	1.25	K/W Typical socket mount
$\text{R}_{\text{thJA}}$	Junction-to-Ambient	—	—	80	
$\text{R}_{\text{thCS}}$	Case-to-Sink	—	0.21	—	

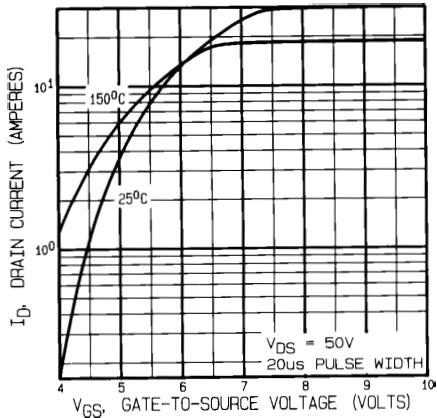
## IRFY440CM Device



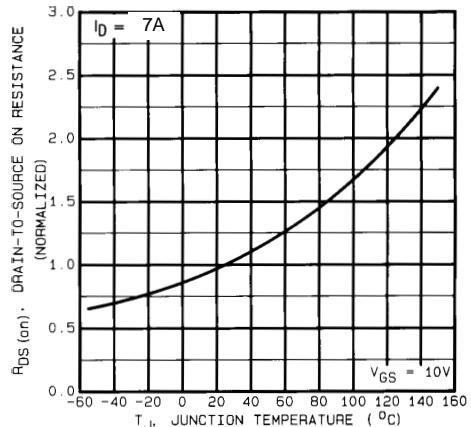
**Fig. 1 — Typical Output Characteristics**  
 $T_C = 25^\circ\text{C}$



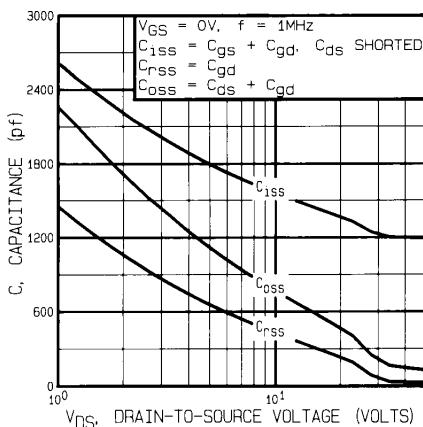
**Fig. 2 — Typical Output Characteristics**  
 $T_C = 150^\circ\text{C}$



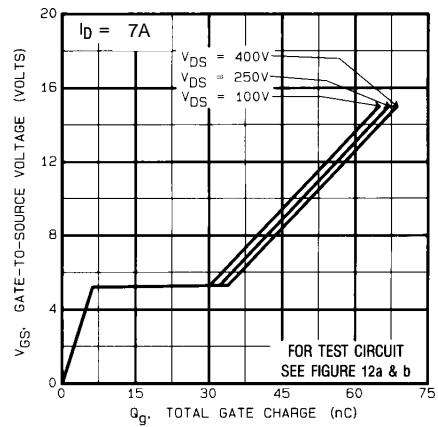
**Fig. 3 — Typical Transfer Characteristics**



**Fig. 4 — Normalized On-Resistance Vs. Temperature**



**Fig. 5 — Typical Capacitance Vs. Drain-to-Source Voltage**



**Fig. 6 — Typical Gate Charge Vs. Gate-to-Source Voltage**

## IRFY440CM Device

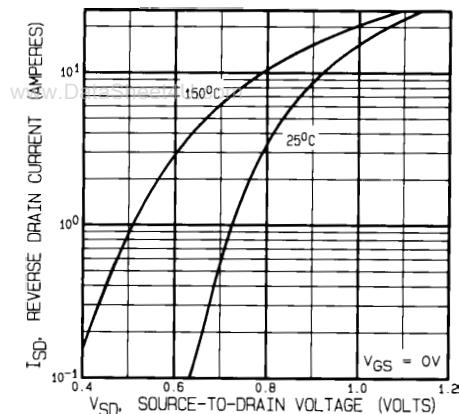


Fig. 7 — Typical Source-to-Drain Diode Forward Voltage

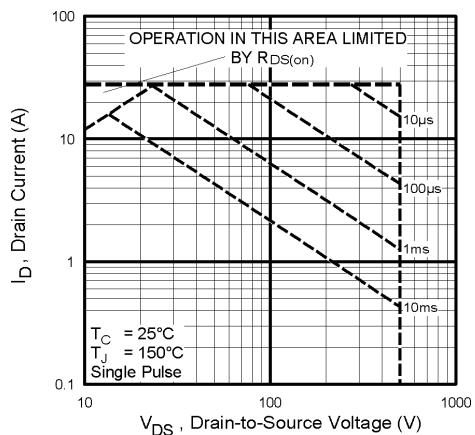


Fig. 8 — Maximum Safe Operating Area

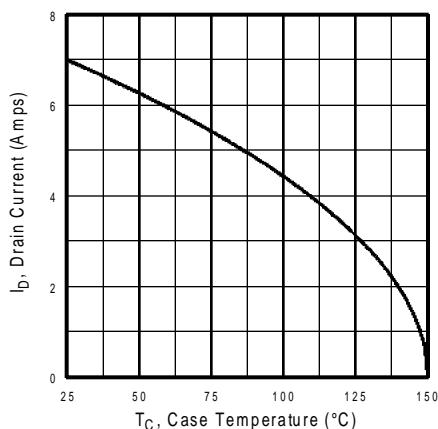


Fig. 9 — Maximum Drain Current Vs. Case Temperature

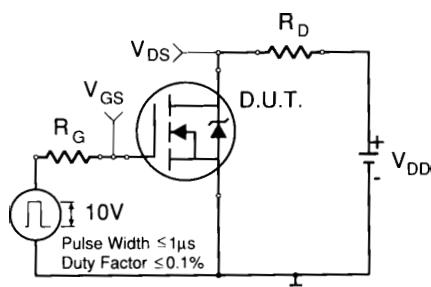


Fig. 10a — Switching Time Test Circuit

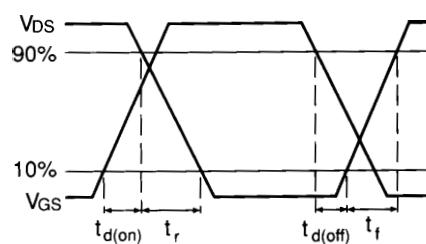


Fig. 10b — Switching Time Waveforms

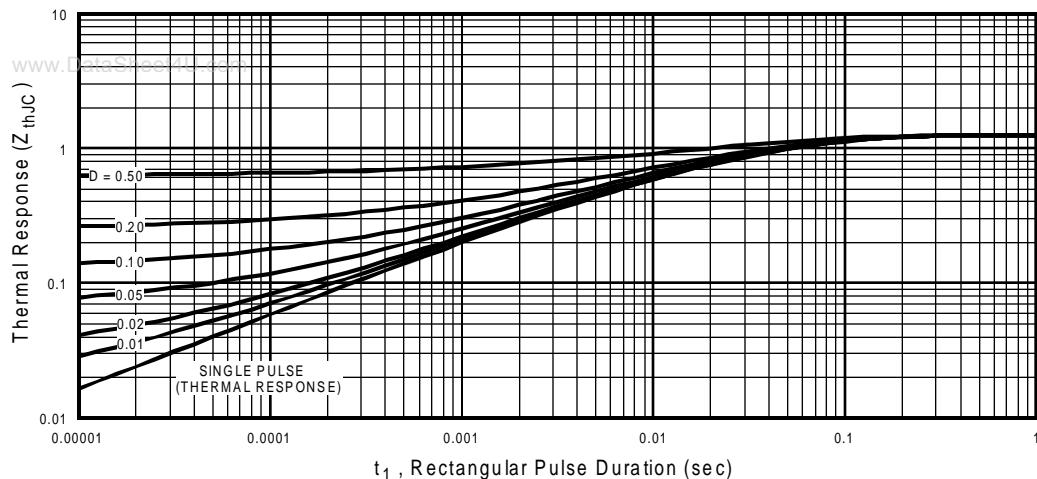


Fig. 11 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

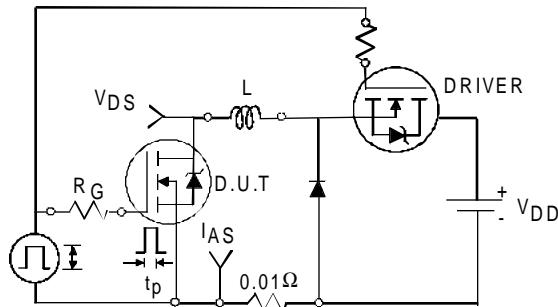


Fig. 12a — Unclamped Inductive Test Circuit

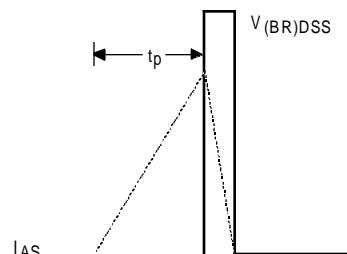


Fig. 12b — Unclamped Inductive Waveforms

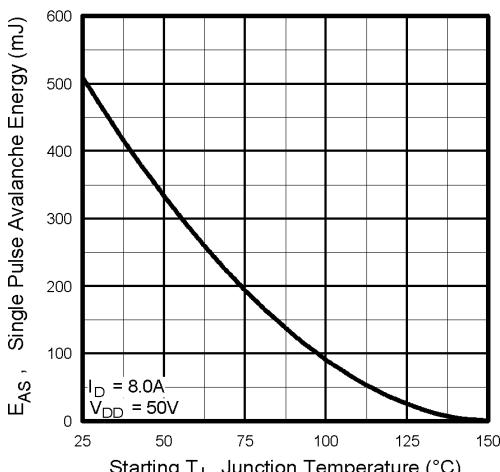


Fig. 12c — Max. Avalanche Energy vs. Current

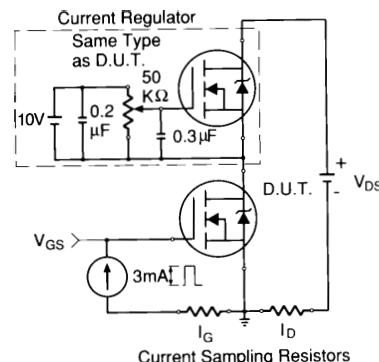


Fig. 13a — Gate Charge Test Circuit  
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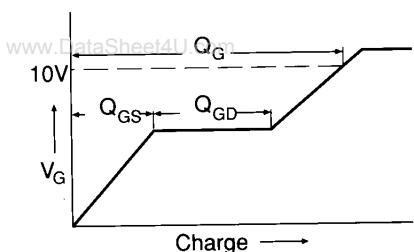
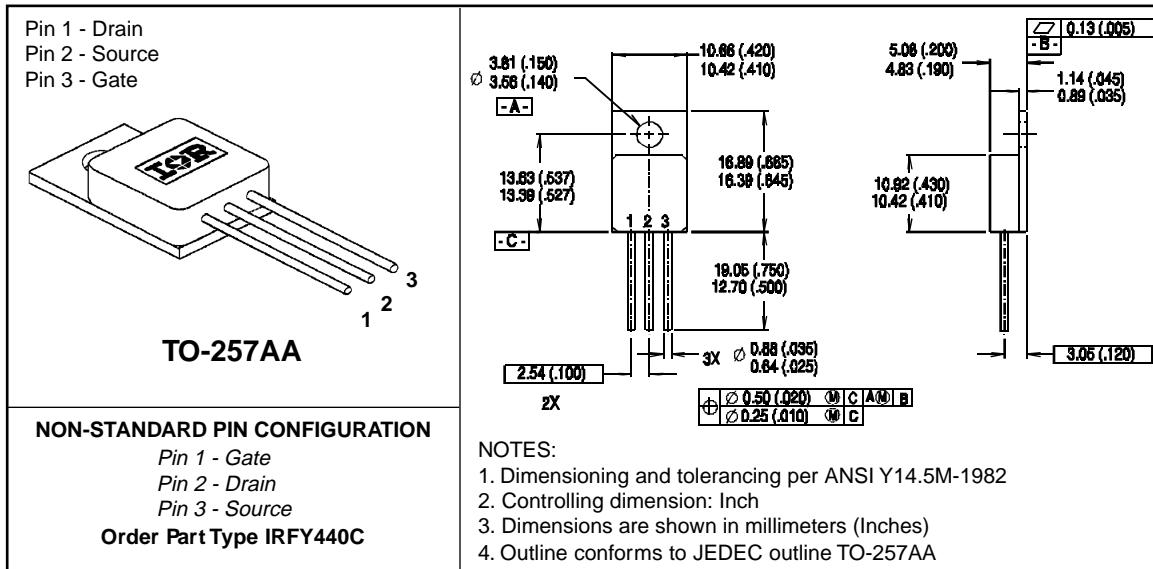


Fig. 13b — Basic Gate Charge Waveform

## Case Outline and Dimensions



### CAUTION

#### BERYLLIA WARNING PER MIL-PRF-19500

Packages containing beryllia shall not be ground, sandblasted, machined or have other operations performed on them which will produce beryllia or beryllium dust. Furthermore, beryllium oxide packages shall not be placed in acids that will produce fumes containing beryllium.

International  
**IR** Rectifier

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**EUROPEAN HEADQUARTERS:** Hurst Green, Oxted, Surrey RH8 9BB, UK Tel: ++ 44(0) 1883 732020

**IR CANADA:** 7321 Victoria Park Ave., Suite 201, Markham, Ontario L3R 2Z8, Tel: (905) 475 1897

**IR GERMANY:** Saalburgstrasse 157, 61350 Bad Homburg Tel: ++ 49 6172 96590

**IR ITALY:** Via Liguria 49, 10071 Borgaro, Torino Tel: ++ 39 11 451 0111

**IR FAR EAST:** K&H Bldg., 2F, 3-30-4 Nishi-Ikeburo 3-Chome, Toshima-Ki, Tokyo Japan 171 Tel: 81 3 3983 0086

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